

Small Signal Diode



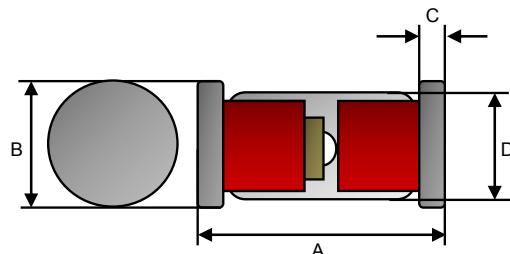
Features

- ◊ Designed for through-Hole Device Type Mounting.
- ◊ Hermetically Sealed Glass.
- ◊ All external surfaces are corrosion resistant and terminals are readily solderable.
- ◊ High reliability glass passivation insuring parameter stability and protection against junction contamination.
- ◊ Pb free version and RoHS compliant

Mechanical Data

- ◊ Case :MINI-MELF hermetically sealed glass
- ◊ Terminal: Pure tin plated, lead free., solderable per MIL-STD-202, Method 208 guaranteed
- ◊ High temperature soldering guaranteed: 270°C/10s
- ◊ Polarity : Indicated by cathode band
- ◊ Weight : 29 ± 2.5 mg

**MINI-MELF (LL34)
HERMETICALLY SEALED GLASS**



Dimensions	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
A	3.30	3.70	0.130	0.146
B	1.40	1.60	0.055	0.063
C	0.25	0.40	0.010	0.016
D	1.25	1.40	0.049	0.055

Ordering Information

Part No.	Package	Packing
LLDB3/LLDB3TG L1	MINI-MELF	2.5Kpcs / 7" Reel

Maximum Ratings and Electrical Characteristics

Rating at 25°C ambient temperature unless otherwise specified.

Maximum Ratings

Type Number	Symbol	Value	Units
Power Dissipation	P _D	150	mW
Repetitive Peak Forward Current Pulse Width= 20μsec	I _{FRM}	2	A
Thermal Resistance (Junction to Ambient) (Note 1)	R _{θJA}	400	°C/W
Junction and Storage Temperature Range	T _J , T _{STG}	-40 to + 125	°C

Electrical Characteristics

Type Number	Symbol	LLDB3TG	LLDB3	Units
Break-over Voltage C= 22nF	V _{BO}	32	32	V
Break-over Voltage Symmetry C= 22nF	+ / - V _{BO}	+ / - 2	+ / - 3	V
Break-over Current C= 22nF	I _{BO}	100	15	nA
Maximum Leakage Current V _R = 0.5V	I _R	10		μA
Junction Capacitance V _R =0, f=1.0MHz	C _J	22.0		nF
Output Voltage	V _O	5		V
Reverse Recovery Time (Note2)	T _{rr}	1.5		μs

Notes:1. Valid provided that electrodes are kept at ambient temperature

Notes:2. Test Condition : I_F=0.5A, R_L=100Ω

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Rating and Shacteristic Curves

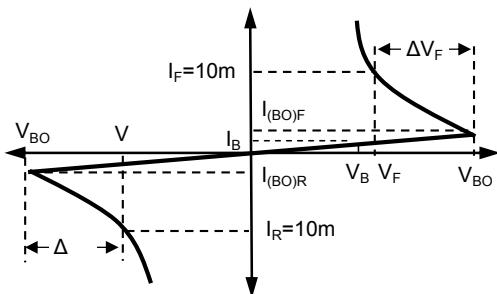


FIG 1 Admissible Power Dissipation Curve

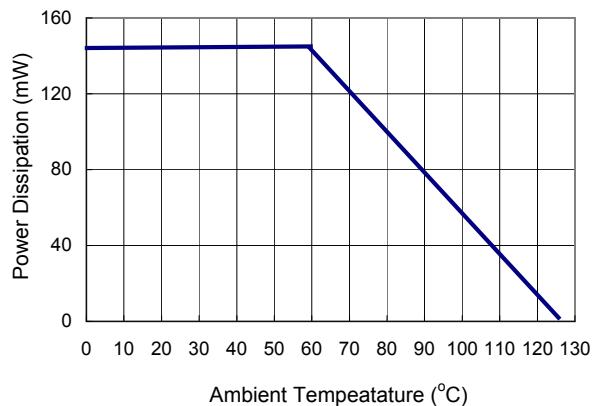


FIG 2 Typical Junction Capacitance

V_{BO} : Break-Over Voltage at I_{BO}
 I_{BO} : Test current for voltage V_{BO}
 V_F : Dynamic impedance at I_F
 I_B : Test current for voltage V_B
 V_B : Voltage at current I_B
 I_R : Test current for voltage V_B

